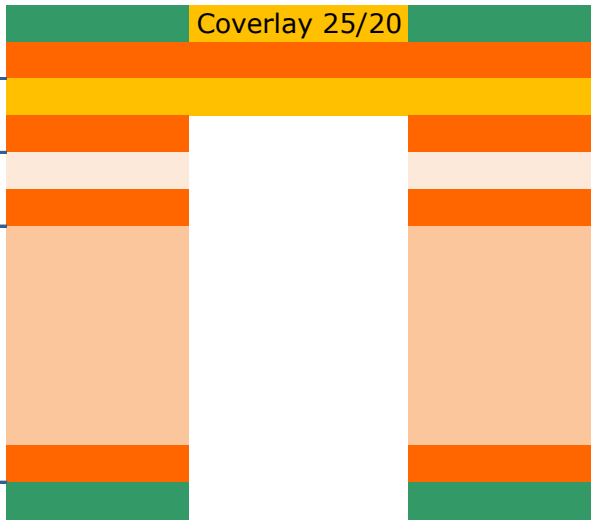
## 4-Layer Rigid-Flex A1



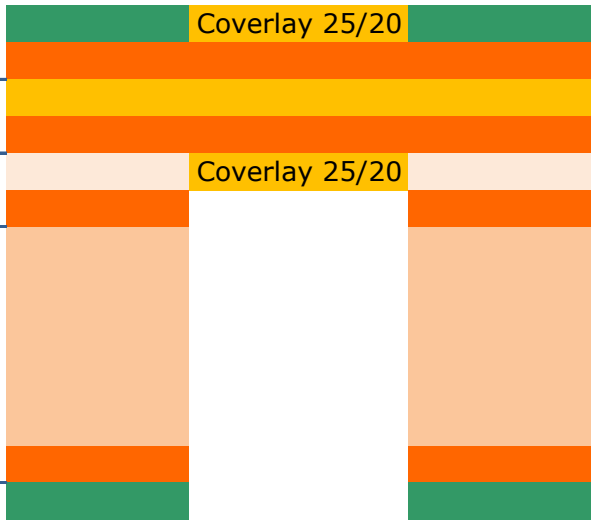

| | | | |
|---|---|---|---|
| | solder mask | 15 µm | Lacquer |
| Top L1 | outer copper | 35 µm | Copper |
| | polyimid | 50 µm | Polyimid |
| IL2 | inner copper | 18 µm | Copper |
| | low flow | 60 µm | Prepreg |
| IL3 | inner copper | 18 µm | Copper |
| | core | 1464 µm | FR4 |
| Bottom L4 | outer copper | 35 µm | Copper |
| | solder mask | 15 µm | Lacquer |
| | **Total finished thickness:** | **1,71 mm** | |
| | Tolerance ± | 10% | |
| | Maximum thickness | 1,881 mm | |
| | Minimum thickness | 1,539 mm | |

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Date: 06.01.2020
Revision: 2.0

| | |
|---|---|
| FR4 core thickness 1,0 mm | 964 µm FR4 |
| FR4 core thickness 1,5 mm | 1464 µm FR4 |
| FR4 core thickness 2,0 mm | 1964 µm FR4 |

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## 4-Layer Rigid-Flex A2



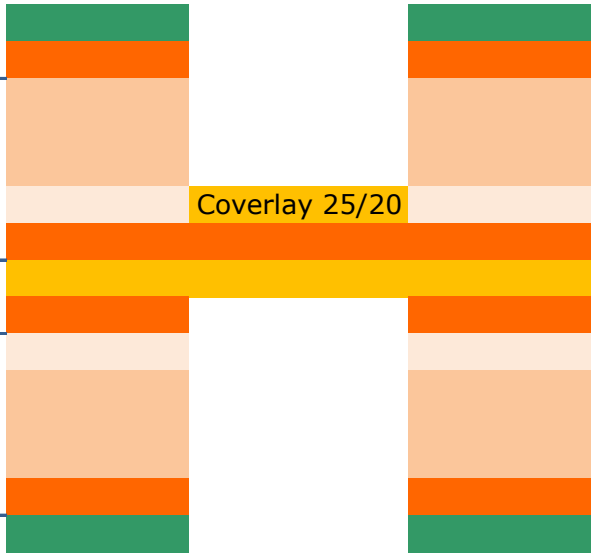

| | | | |
|---|---|---|---|
| | solder mask | 15 | µm Lacquer |
| Top L1 | outer copper | 35 | µm Copper |
| | polyimid | 50 | µm Polyimid |
| IL2 | inner copper | 18 | µm Copper |
| | low flow | 60 | µm Prepreg |
| IL3 | inner copper | 18 | µm Copper |
| | core | 1464 | µm FR4 |
| Bottom L4 | outer copper | 35 | µm Copper |
| | solder mask | 15 | µm Lacquer |
| | **Total finished thickness:** | **1,71** | **mm** |
| | Tolerance ± | 10% | |
| | Maximum thickness | 1,881 | mm |
| | Minimum thickness | 1,539 | mm |

Editor: SKA
Date: 06.01.2020
Revision: 2.0

| | | |
|---|---|---|
| FR4 core thickness 1,0 mm | 964 | µm FR4 |
| FR4 core thickness 1,5 mm | 1464 | µm FR4 |
| FR4 core thickness 2,0 mm | 1964 | µm FR4 |

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## 4-Layer Rigid-Flex I1




| | | | |
|---|---|---|---|
| | solder mask | 15 µm | Lacquer |
| Top L1 | outer copper | 35 µm | Copper |
| | core | 564 µm | FR4 |
| | low flow | 60 µm | Prepreg |
| IL2 | inner copper | 18 µm | Copper |
| | polyimid | 50 µm | Polyimid |
| IL3 | inner copper | 18 µm | Copper |
| | low flow | 60 µm | Prepreg |
| | core | 564 µm | FR4 |
| Bottom L4 | outer copper | 35 µm | Copper |
| | solder mask | 15 µm | Lacquer |

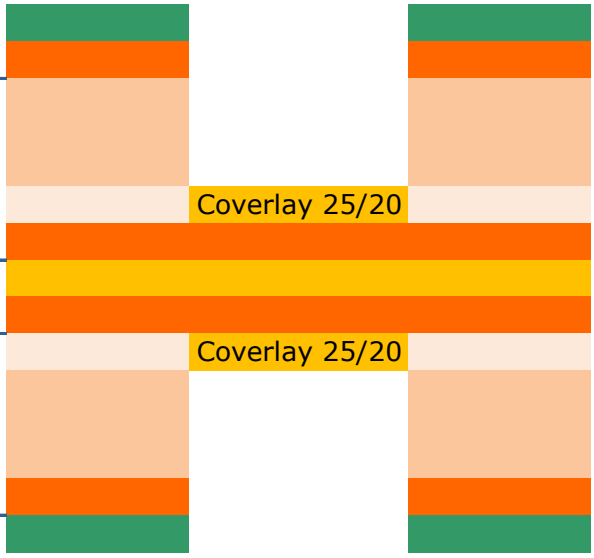
| | | |
|---|---|---|
| **Total finished thickness:** | **1,43** | **mm** |
| Tolerance ± | 10% | |
| Maximum thickness | 1,577 | mm |
| Minimum thickness | 1,291 | mm |

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Date: 06.01.2020
Revision: 2.0

| | | |
|---|---|---|
| FR4 core thickness 1,0 mm | 364 µm | FR4 |
| FR4 core thickness 1,5 mm | 564 µm | FR4 |
| FR4 core thickness 2,0 mm | 964 µm | FR4 |

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## 4-Layer Rigid-Flex I2




| | | | |
|---|---|---|---|
| | solder mask | 15 µm | Lacquer |
| Top L1 | outer copper | 35 µm | |
| | core | 564 µm | FR4 |
| | low flow | 60 µm | Prepreg |
| IL2 | inner copper | 18 µm | Copper |
| | polyimid | 50 µm | Polyimid |
| IL3 | inner copper | 18 µm | Copper |
| | low flow | 60 µm | Prepreg |
| | core | 564 µm | FR4 |
| Bottom L4 | outer copper | 35 µm | Copper |
| | solder mask | 15 µm | Lacquer |
| | **Total finished thickness:** | **1,43 mm** | |
| | Tolerance ± | 10% | |
| | Maximum thickness | 1,577 mm | |
| | Minimum thickness | 1,291 mm | |

Editor: SKA
Date: 06.01.2020
Revision: 2.0

| | | |
|---|---|---|
| FR4 core thickness 1,0 mm | 364 µm | FR4 |
| FR4 core thickness 1,5 mm | 564 µm | FR4 |
| FR4 core thickness 2,0 mm | 964 µm | FR4 |

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